

## **REMARKS**

Applicants acknowledge the allowance of claims 10-15. Further, Applicants add new independent claims 21 and 22 and amend independent claims 1 and 16 for clarification. The amendments introduce no new matter and further, are fully supported by the specification. Accordingly, Applicants respectfully request entry and examination of claims 1-9 and 16-22.

### **Claim Rejections Under 35 U.S.C. § 103(a)**

The Examiner rejected claims 1-9 and 16-20 under 35 U.S.C. § 103(a) as being unpatentable over Pant et al. (U.S. Patent No. 5,916,012). Applicants respectfully traverse.

The newly added claims and clarifying amendments are fully supported in the specification at page 10, lines 20-22. Thus, no new matter is introduced by way of the clarifying amendments.

Applicants respectfully traverse the rejection regarding the structure disclosed in Pant et al. The structure results in uniform polishing of a wafer surface by dispensing pressurized fluid against a support housing underlying a polishing pad. The support housing has multiple openings that dispense pressurized fluid to the underside of the polishing pad. In particular, the multiple openings permit the polishing of the wafer. The reference further discloses that the multiple openings are arranged within a circumference of the support housing, such that the openings fully oppose the wafer. See Figures 3, 5, 6, 8 and text of the detailed description. Specifically, the multiple openings only apply pressurized fluid within the circumference.

Correspondingly, no Figure illustrates openings outside the circumference of the support housing for dispensing pressurized fluid to an area outside the circumference. Thus, the reference provides no suggestion to include openings outside the circumference for polishing an area outside the circumference.

In contrast, Applicants' independent claims 1 and 16 recite two sets of pressure sub regions of a platen. The inner set of pressure sub regions has radial rows that provide pressure to a polishing pad above the platen. Each inner pressure sub region is below the wafer and is *within* an about 300mm circumference. Further, an

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outer set of pressure sub regions has radial rows that provide pressure to the polishing pad above the platen. Each outer pressure sub region is below the wafer and is *outside* the about 300mm circumference. Similarly, Applicants' independent claims 21 and 22 recite two sets of the inner and outer pressure sub regions of a platen for an about 200mm circumference. Thus, while the independent claims recite radial rows inside and outside the 200mm or 300mm circumference, the reference only teaches and suggests openings within the circumference.

Accordingly, Applicants respectfully submit that the pending claims are in condition for allowance. If the Examiner has any questions concerning the response, the Examiner is kindly requested to contact the undersigned at (408) 749-6900. If any other fees are due in connection with filing this amendment, the Commissioner is also authorized to charge Deposit Account No. 50-0805 (Order No. LAM2P238.CIP).

Respectfully submitted,  
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